

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0432028918](#)  
**Status:** **Active**  
**Overview:** [modular\\_plugs\\_jacks](#)  
**Description:** Modular Jack, Right Angle, Low Profile, Shielded, Offset Panel Grounding Tabs, with Bottom Grounding Tab, Front Position PCB Ground Tab, 8/8

**Documents:**

[3D Model](#) [Product Specification PS-43202-001 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

CSA LR19980  
 UL E107635

**General**

Product Family Modular Jacks/Plugs  
 Series [43202](#)  
 Comments Enhanced panel grounding tabs  
 Component Type PCB Jack  
 Magnetic No  
 Overview [modular\\_plugs\\_jacks](#)  
 Performance Category 3  
 Power over Ethernet (PoE) N/A  
 Product Name RJ45

**Physical**

Color - Resin Black  
 Durability (mating cycles max) 500  
 Flammability 94V-0  
 Inverted / Top Latch No  
 Lightpipes/LEDs None  
 Material - Metal Brass, Phosphor Bronze  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin  
 Material - Resin High Temperature Thermoplastic  
 Orientation Right Angle (Side Entry)  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.062 In  
 PCB Thickness Recommended (mm) 1.60 mm  
 Packaging Type Tray  
 Panel Mount With Flange  
 Pitch - Mating Interface (in) 0.050 In  
 Pitch - Mating Interface (mm) 1.27 mm  
 Plating min: Mating (µin) 50  
 Plating min: Mating (µm) 1.25  
 Plating min: Termination (µin) 100  
 Plating min: Termination (µm) 2.5  
 Ports 1  
 Positions / Loaded Contacts 8/8  
 Surface Mount Compatible (SMC) Yes  
 Temperature Range - Operating -40°C to +85°C  
 Termination Interface: Style Through Hole  
 Wire/Cable Type N/A

**Electrical**

Current - Maximum per Contact 1.5A



**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC**  
 Not Reviewed  
**Halogen-Free Status**  
 Not Reviewed

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[43202Series](#)

**Mates With**

FCC 68 Plugs

Grounding to PCB	Yes
Grounding to Panel	Offset Panel Ground Tabs
Shielded	Yes
Voltage - Maximum	125V

**Solder Process Data**

Lead-free Process Capability	Wave Capable (TH only)
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**Material Info****Reference - Drawing Numbers**

Packaging Specification	PK-43202-004
Product Specification	PS-43202-001, RPS-43202-002
Sales Drawing	SDA-43202

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SHIELDED MODULAR JACK SHOWN WITH PANEL GROUND OPTION 'D' AND FRONT PCB GROUND TABS.

NOTES:

- 1) MATERIAL:
  - HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
  - INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
  - TERMINALS: PHOSPHOR BRONZE, .012/ 0.30 THICK
  - SHIELD: BRASS, .007/ 0.18 THICK
- 2) FINISH:
  - TERMINALS:
    - A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN., \*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
    - B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN., \*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
    - \*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
  - SHIELD:
    - 100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES / 1.27 MICROMETERS COPPER UNDERPLATE PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43202.
- 4) PACKAGING SPECIFICATION:
  - UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43202-003.
  - UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES PER MOLEX PACKAGING SPECIFICATION PK-43202-005.
  - SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43202-004.
- 5) SEE SHEETS 7 - 9 FOR P.C. BOARD LAYOUTS.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

9	L2
8	L2
7	L2
6	L4
5	L
4	K2
3	L1
2	L1
1	L4
SH	REV

DRAWING LEGEND

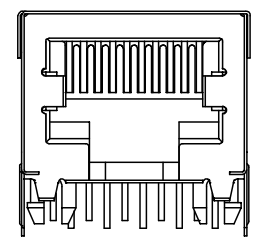
- SHEET 1- NOTES, DRAWING LEGEND
- SHEET 2- SHIELDED MODULAR JACK W/ BOTTOM GROUND TABS
- SHEET 3- SHIELDED MODULAR JACK W/O BOTTOM GROUND TABS
- SHEET 4- UNSHIELDED MODULAR JACK
- SHEET 5- PART NUMBER CHARTS
- SHEET 6- PART NUMBER CHARTS
- SHEET 7- FOOTPRINT LAYOUT FOR 4 POSITION HOUSING
- SHEET 8- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING
- SHEET 9- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING

OBS COLORED JACKS EC NO: UCP2008-1189 DRAWN:JBELL 2007/11/30 CHKD:LSCHMIDT 2008/02/20 APPR:FSM1TH 2008/03/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▼=0 ▽=0	mm INCH	IN/MM	4:1	INCH		
		4 PLACES ±--- ±--- 3 PLACES ±--- ±.010 2 PLACES ±0.25 ±.014 1 PLACE ±0.36 ±---	DRAWN BY DATE JTR 1993/03/31	CHECKED BY DATE JTR 1993/03/31	TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY		
		ANGULAR ±1/2°	APPROVED BY DATE RAS 1993/03/31	MATERIAL NO. SEE SHTS 5&6			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DOCUMENT NO. SDA-43202		SHEET NO. 1 OF 9		
L4	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

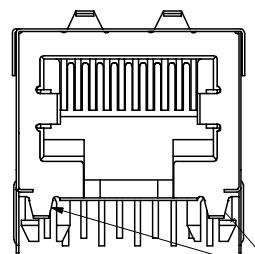
# SHIELDED MODULAR JACK W/BOTTOM GROUND TABS

SIZE 8 LOADED 10 VERSION SHOWN

## SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



**OPTION "A"**  
NO TOP OR SIDE TABS

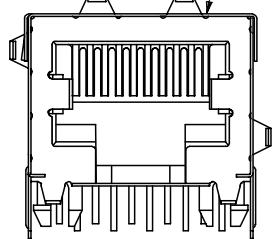


**OPTION "B"**  
TOP TABS

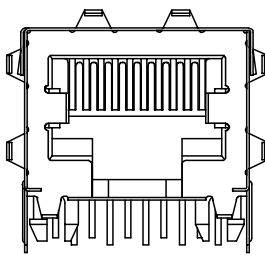
BOTTOM GROUND TABS

OPTIONAL TOP GROUND TABS

SHIELDED MODULAR JACK ASSEMBLY  
SEE SHEET 5 FOR MATERIAL NO.

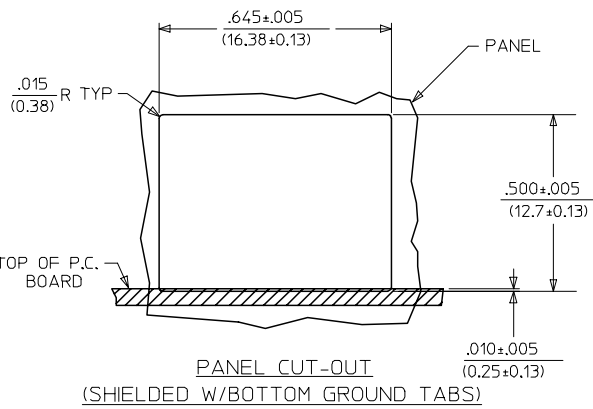
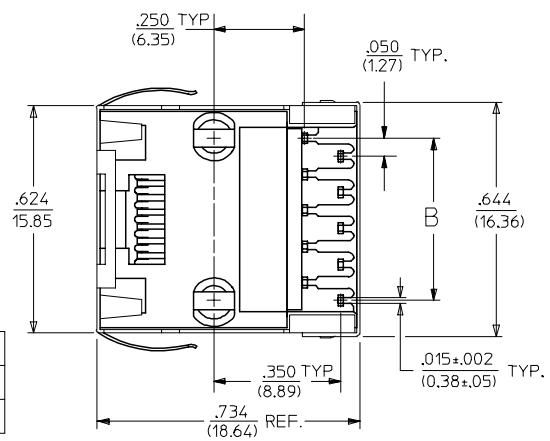
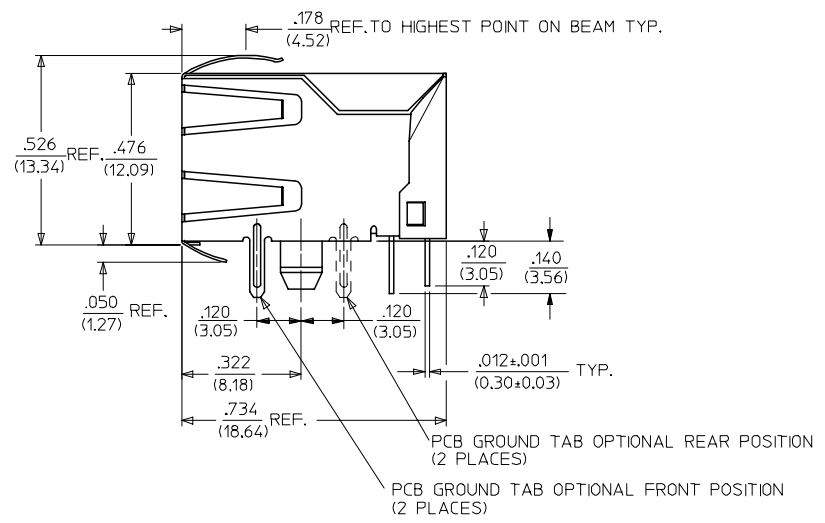


**OPTION "C"**  
TOP AND STAGGERED SIDE TABS



**OPTION "D"**  
TOP AND SIDE TABS

OPTIONAL SIDE GROUND TABS  
(2 PLACES)



HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450±.005 11.43±.13
8	8	.350±.005 8.89±.13

SEE SHEET ONE FC NO: UCP2004-1888 DRWN: LSCHMIDT 2004/03/31 CHKD: LSCHMIDT 2004/03/31 APPR: FSMITH 2004/03/31 L1	QUALITY SYMBOLS ▽ - 0 ▽ - 0	GENERAL TOLERANCES (UNLESS SPECIFIED) 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ±1/2°	SCALE 4:1 DIMENSION STYLE IN/MM	DESIGN UNITS INCH DRAWN BY JTR DATE 1993/03/31 CHECKED BY JTR DATE 1993/03/31 APPROVED BY RAS DATE 1993/03/31	THIRD ANGLE PROJECTION REVISE ON CAD ONLY	ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY	
		MOLEX MOLEX INCORPORATED					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 2 OF 9
		SEE SHT 5 SDA-43202					SHEET NO. 2 OF 9

SHIELDED MODULAR JACKS W/BOTTOM GROUND TABS (SHEET 2)

ASSEMBLY MATERIAL NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	TERMINAL PLATING OPTION	PACKAGING OPTION	HOUSING COLOR
43202-8900	8	10	A	FRONT POSITION	A	TRAY	BLACK
43202-8901	8	10	B	FRONT POSITION	A	TRAY	
43202-8902	8	10	C	FRONT POSITION	A	TRAY	
43202-8903	8	10	D	FRONT POSITION	A	TRAY	
43202-8908	8	10	A	REAR POSITION	A	TRAY	
43202-8909	8	10	B	REAR POSITION	A	TRAY	
43202-8910	8	10	C	REAR POSITION	A	TRAY	
43202-8911	8	10	D	REAR POSITION	A	TRAY	
43202-8916	8	8	A	FRONT POSITION	A	TRAY	
43202-8917	8	8	B	FRONT POSITION	A	TRAY	
43202-8918	8	8	C	FRONT POSITION	A	TRAY	
43202-8919	8	8	D	FRONT POSITION	A	TRAY	
43202-8924	8	8	A	REAR POSITION	A	TRAY	
43202-8925	8	8	B	REAR POSITION	A	TRAY	
43202-8926	8	8	C	REAR POSITION	A	TRAY	
43202-8927	8	8	D	REAR POSITION	A	TRAY	

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A

SEE SHEET 1 EC NO: UCP2004-1347 DRWN:MKANARAO004/02/09 CHKD:MKANARAO004/02/09 APPR:BMURKUS 2004/02/10 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
		mm INCH	DIMENSION STYLE IN/MM	TITLE	ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY MOLEX INCORPORATED	
		4 PLACES ± --- ± ---	DRAWN BY DATE	JTR 1993/03/18		
		3 PLACES ± --- ±.010	CHECKED BY DATE	JTR 1993/03/18		
2 PLACES ± 0.25 ±.014	APPROVED BY DATE	RAS 1993/03/18	MATERIAL NO. DOCUMENT NO. SHEET NO.	SEE CHART SDA-43202 5 OF 9		
1 PLACE ± 0.36 ± ---	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



PC BOARD LAYOUT FOR 8 POSITION HOUSING  
(10 CIRCUIT FOOTPRINT SHOWN)  
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING  
(8 CIRCUIT FOOTPRINT SHOWN)  
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING  
(16 CIRCUIT FOOTPRINT SHOWN)  
(COMPONENT SIDE OF BOARD)

NOTES:  
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

ADD PCB THICKNESS EC NO: UCP2005-2739 DRWN: L.SCHMIDT 2005/06/20 CHKD: ELHAG 2005/06/22 APPR: F.SMITH 2005/06/23 REV: L2	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	-0 -0	mm	INCH	DIMENSION STYLE IN/MM		TITLE		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± .010	2 PLACES ± 0.25 ± .014	1 PLACE ± 0.36 ± ---	DRAWN BY L.E.LENZ	DATE 1995/03/09	ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY
		ANGULAR ±1/2°				CHECKED BY JTR	DATE 1995/03/09	
DRAFT WHERE APPLICABLE		MUST REMAIN WITHIN DIMENSIONS		APPROVED BY RAS	DATE 1995/03/09	SHEET NO. 9 OF 9		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								